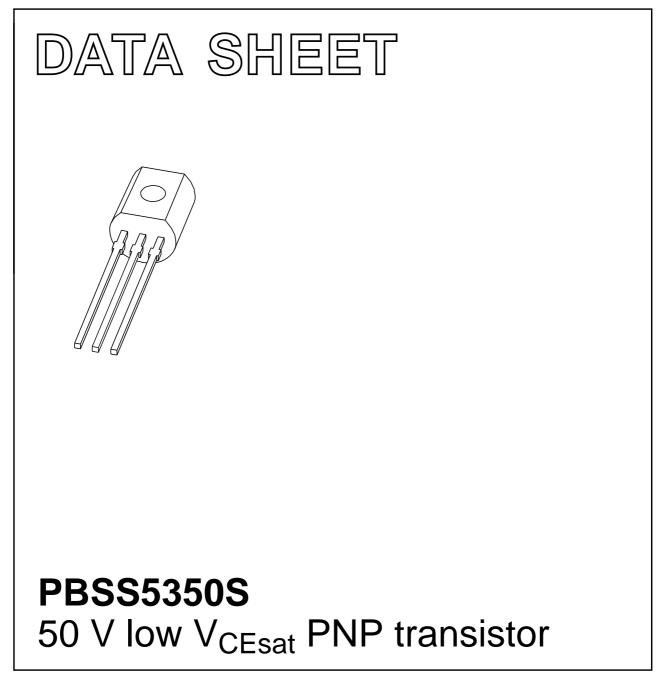
## DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Nov 19 2004 Aug 20



# 50 V low V<sub>CEsat</sub> PNP transistor

### PBSS5350S

#### FEATURES

- High power dissipation (830 mW)
- Ultra low collector-emitter saturation voltage
- 3 A continuous current
- High current switching
- Improved device reliability due to reduced heat generation.

#### APPLICATIONS

- Medium power switching and muting
- Linear regulators
- DC/DC convertor
- Supply line switching circuits
- Battery management applications
- Strobe flash units
- Heavy duty battery powered equipment (motor and lamp drivers).

#### DESCRIPTION

PNP low V<sub>CEsat</sub> transistor in a SOT54 plastic package. NPN complement: PBSS4350S.

#### MARKING

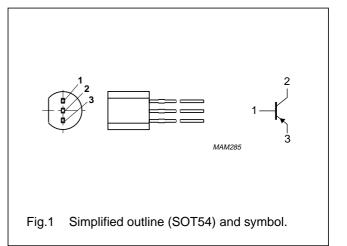
TYPE NUMBER	MARKING CODE	
PBSS5350S	S5350S	

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	-50	V
I <sub>C</sub>	collector current (DC) -3		А
I <sub>CM</sub>	peak collector current		A
R <sub>CEsat</sub>	Esat equivalent on-resistance <150 ms		mΩ

#### PINNING

PIN	DESCRIPTION	
1	base	
2	collector	
3	emitter	



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	-60	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-6	V
I <sub>C</sub>	collector current (DC)		-	-3	А
I <sub>CM</sub>	peak collector current		-	-5	А
I <sub>BM</sub>	peak base current		-	-1	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	830	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated and standard footprint.

### PBSS5350S

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	PARAMETER CONDITIONS		UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	in free air; note 1	150	K/W	

#### Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated and standard footprint.

#### CHARACTERISTICS

 $T_{amb}$  = 25 °C unless otherwise specified.

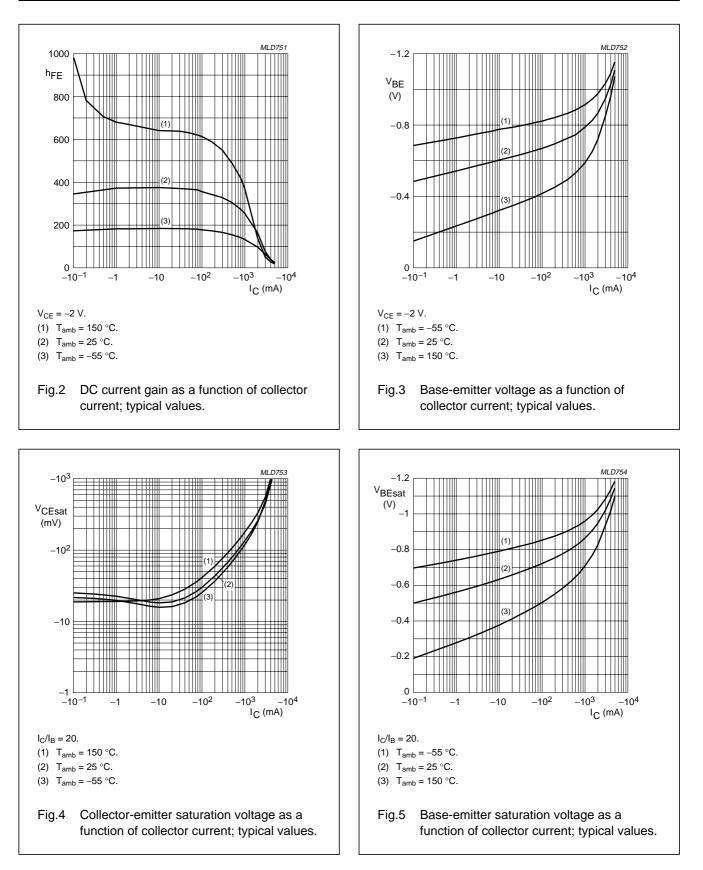
SYMBOL	YMBOL PARAMETER CONDITIONS		MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -50 \text{ V}; I_E = 0$	_	-	-100	nA
		$V_{CB} = -50 \text{ V}; I_E = 0; T_j = 150 \text{ °C}$	-	-	-50	μA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; \text{ I}_{C} = 0$	-	-	-100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -2 \text{ V}; \text{ I}_{C} = -500 \text{ mA}$	200	-	-	
		$V_{CE} = -2 \text{ V}; I_{C} = -1 \text{ A}; \text{ note } 1$	200	-	-	
		$V_{CE} = -2 \text{ V}; I_{C} = -2 \text{ A}; \text{ note } 1$	100	-	-	
V <sub>CEsat</sub>	collector-emitter saturation	I <sub>C</sub> = -500 mA; I <sub>B</sub> = -50 mA	-	-	-100	mV
	voltage	$I_{C} = -1 \text{ A}; I_{B} = -50 \text{ mA}$	-	-	-180	mV
		$I_{\rm C} = -2$ A; $I_{\rm B} = -200$ mA; note 1	-	-	-300	mV
R <sub>CEsat</sub>	equivalent on-resistance	$I_{C} = -2 \text{ A}; I_{B} = -200 \text{ mA}; \text{ note } 1$	-	120	<150	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage	on $I_{\rm C} = -2$ A; $I_{\rm B} = -200$ mA; note 1		-	-1.2	V
V <sub>BE</sub>	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V}; I_{C} = -1 \text{ A}; \text{ note } 1$	-	-	-1.1	V
f <sub>T</sub>	transition frequency	$I_{C} = -100 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ f} = 100 \text{ MHz}$	100	_	-	MHz
C <sub>c</sub>	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = I_e = 0; f = 1 \text{ MHz}$	-	-	40	pF

#### Note

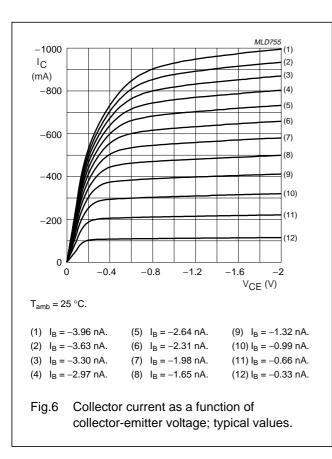
1. Pulse test:  $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$ 

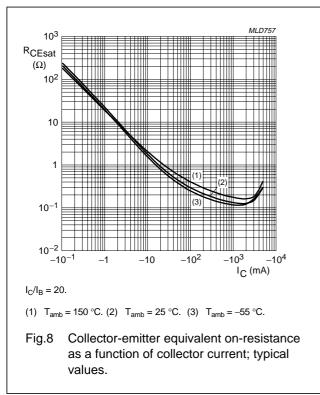
### 50 V low V<sub>CEsat</sub> PNP transistor

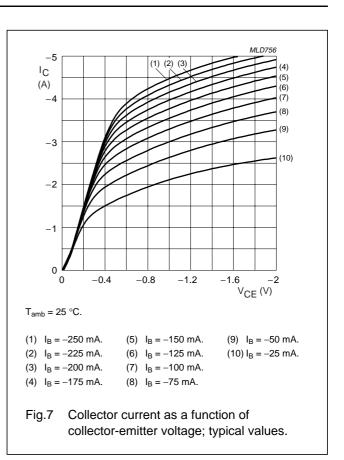
### PBSS5350S



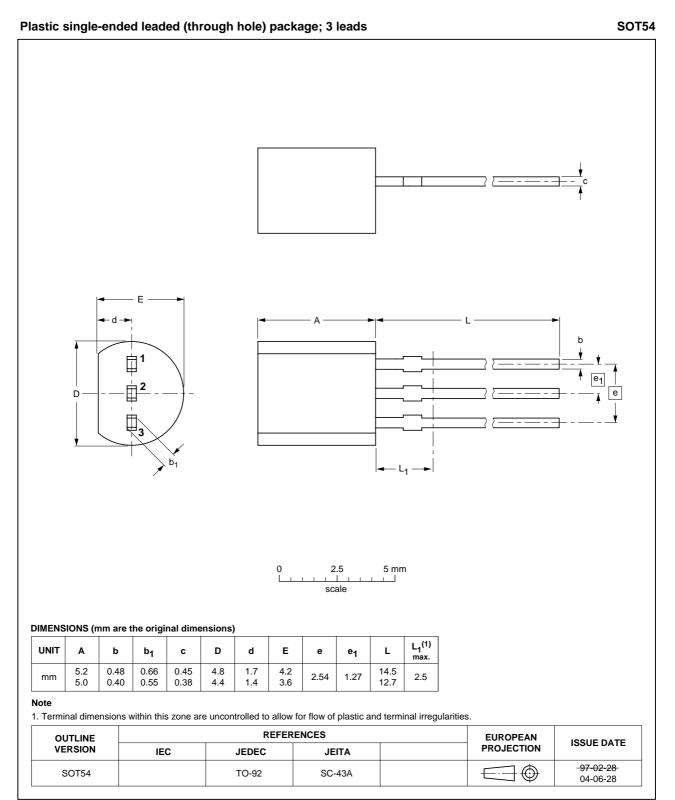
### PBSS5350S







#### PACKAGE OUTLINE



**PBSS5350S** 

PBSS5350S

#### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

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- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

#### DEFINITIONS

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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